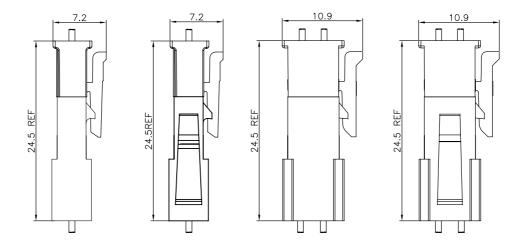


Specifications

Temperature range: $-40^{\circ}\text{C} \sim +105^{\circ}\text{C}$ Voltage rating: 250V Current rating: 5A Contact resistance: $10\text{m}\Omega$ Max Insulation resistance: $1000\text{M}\Omega$ Min Withstand voltage: 1000V AC

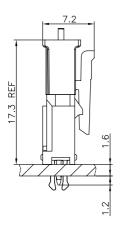
Assembly layout

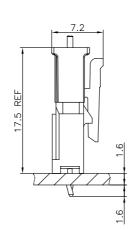
wire to wire

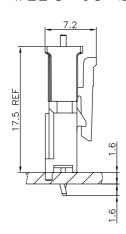


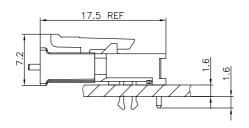
Assembly layout

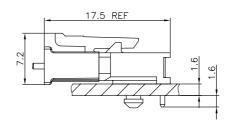
wire to board



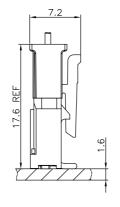


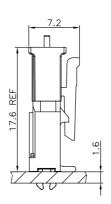


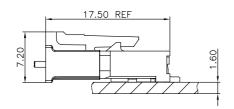


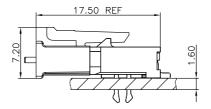


Single row DIP Type







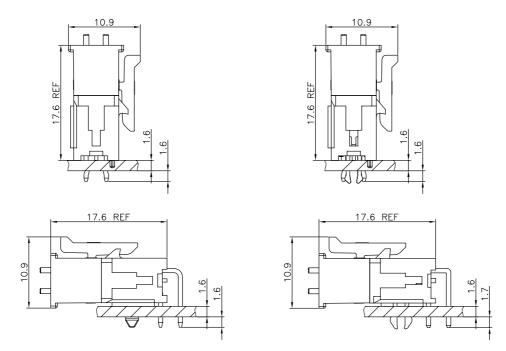


Single row SMT Type

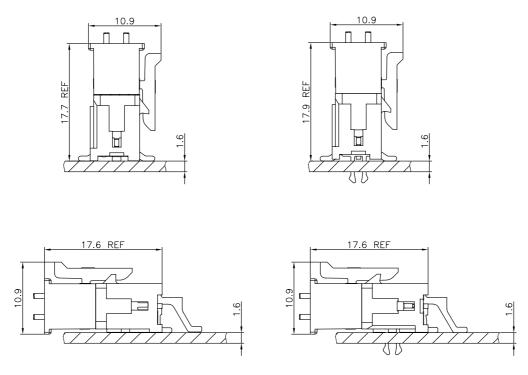


Assembly layout

wire to board



Double row DIP Type

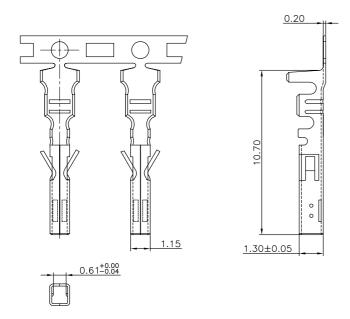


Double row SMT Type



C3030TFX-X

Pitch 3.00mm Terminal



Specifications

MATERIAL SPECIFICATION:
Terminal: Phosphor Bronze

PLATING SPECIFICATION:
Bright tin

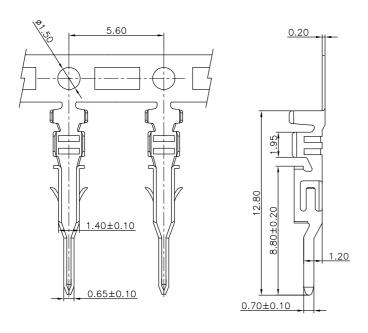
APPLICABLE WIRES:AWG #20-#24
SUITABLE C3030 series Male housing

C3030 T F X-X

SERIES NO:
PLATING:
A-ALL AU G/F
C-BRIGHT TIN
1-G/F
MALE FEMALE:
P-PHOSPHOR BRONZE
B-BRASS

C3030TMX-X

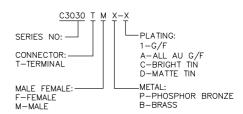
Pitch 3.00mm Terminal



Specifications

MATERIAL SPECIFICATION:
Terminal: Phosphor Bronze
PLATING SPECIFICATION:
Bright tin

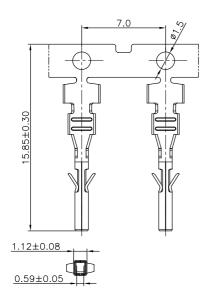
APPLICABLE WIRES:AWG #20-#24 SUITABLE C3030 series Female housing

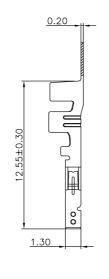




C3030T1FX-X

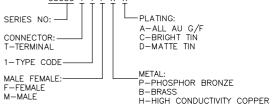
Pitch 3.00mm Terminal





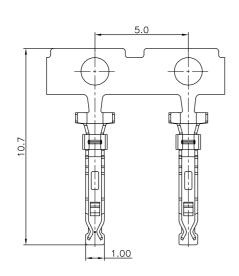
Specifications

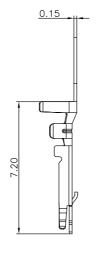
MATERIAL SPECIFICATION: Terminal: High conductivity copper PLATING SPECIFICATION: APPLICABLE WIRES:AWG #16-#18
SUITABLE C3030 series Male housing C3030 T 1 F X-X -PLATING:



C3030T2FX-X

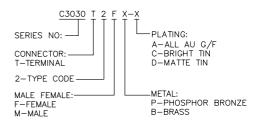
Pitch 3.00mm Terminal





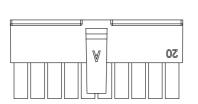
Specifications

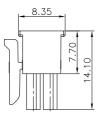
MATERIAL SPECIFICATION: Terminal: Phosphor Bronze PLATING SPECIFICATION: Bright tin APPLICABLE WIRES:AWG #28 SUITABLE C3030 series Male housing

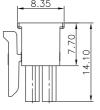


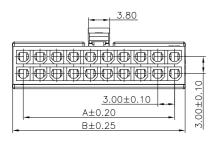
C3030HM-2XXXX

Pitch 3.00mm Double row Housing



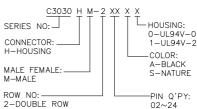






Specifications

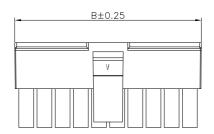
MATERIAL SPECIFICATION: Housing: PA66,94V-0/94V-2 Suitable C3030 series Terminal Mates With C3030 series Wafer

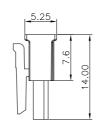


Circuit	Dimensio	ns (mm)	0	Dimensions (mm)		
	Α	В	Circuit	Α	В	
2*01		5.50	2*07	18.00	22.00	
2*02		8.50	2*08	21.00	25.00	
2*03	6.00	10.00	2*09	24.00	28.00	
2*04	9.00	13.00	2*10	27.00	31.00	
2*05	12.00	16.00	2*11	30.00	34.00	
2*06	15.00	19.00	2*12	33.00	37.00	

C3030HM-1XXXX

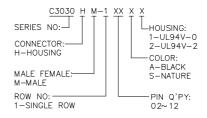
-Pitch 3.00mm Single row Housing





Specifications

MATERIAL SPECIFICATION: Housing: PA66,94V-0/94V-2 Suitable C3030 series Terminal Mates With C3030 series Wafer



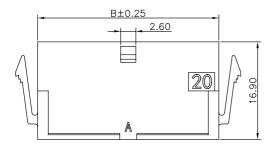
	Dimension	ons(mm)		Dimensions(mm)		
Circuit	Α	В	Circuit	Α	В	
02		8.30	08	21.00	24.80	
03	6.00	9.80	09	24.00	27.80	
04	9.00	12.80	10	27.00	30.80	
05	12.00	15.80	11	30.00	33.80	
06	15.00	18.80	12 33.00 36.80			
07	18.00	21.80				

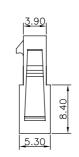
5.00±0.10 Circuit 1 DOOOOOOO 3.00±0.10 A±0.20

C3030HF-1XXXX

Pitch 3.00mm Single row Housing

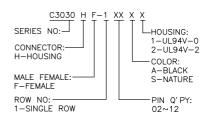
3.00±0.10





Specifications

MATERIAL SPECIFICATION: Housing: PA66,94V-0/94V-2 Suitable C3030 series Terminal Mates With C3030 series Male housing



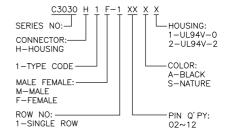
Circuit	Dimensio	ons(mm)	Circuit	Dimensions(mm)		
Circuit	Α	A B		Α	В	
02		6.95	08	21.00	24.95	
03	6.00	9.95	09	24.00	27.95	
04	9.00	12.95	10	27.00	30.95	
05	12.00	15.95	11	30.00	33.95	
06	15.00	18.95	12 33.00 36.95		36.95	
07	18.00	21.95				

C3030H1F-1XXXX

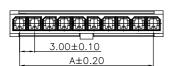
-Pitch 3.00mm Single row Housing

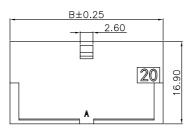
Specifications

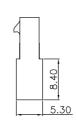
MATERIAL SPECIFICATION: Housing: PA66,94V-0/94V-2 Suitable C3030 series Terminal Mates With C3030 series Male housing



Circuit	Dimensio	ns(mm)	Circuit	Dimensions(mm)		
Circuit	Α	В	Circuit	Α	В	
02		6.95	08	21.00	24.95	
03	6.00	9.95	09	24.00	27.95	
04	9.00	12.95	10	27.00	30.95	
05	12.00	15.95	11	30.00	33.95	
06	15.00	18.95	12	33.00	36.95	
07	18.00	21.95				



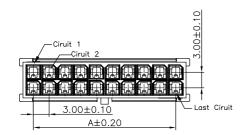


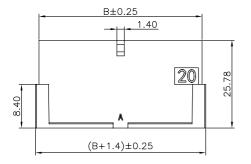




C3030HF-2XXXX

-Pitch 3.00mm Double row Housing

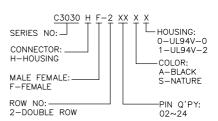






Specifications

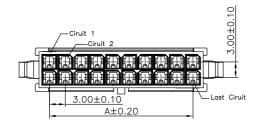
MATERIAL SPECIFICATION:
Housing: PA66,94V-0/94V-2
Suitable C3030 series Terminal
Mates With C3030 series Male housing

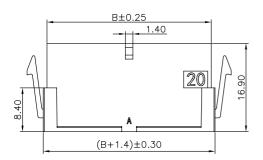


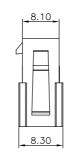
Circuit	Dimensio	ons(mm)	Circuit	Dimensions(mm)		
Circuit	Α	В		Α	В	
2*01		3.95	2*07	18.00	21.95	
2*02		6.95	2*08	21.00	24.95	
2*03	6.00	9.95	2*09	24.00	27.95	
2*04	9.00	12.95	2*10	27.00	30.95	
2*05	12.00	15.95	2*11	30.00	33.95	
2*06	15.00	18.95	2*12	33.00	36.95	

C3030H1F-2XXXX

Pitch 3.00mm Double row Housing

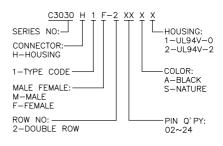






Specifications

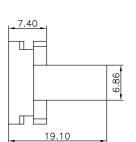
MATERIAL SPECIFICATION:
Housing: PA66,94V-0/94V-2
Suitable C3030 series Terminal
Mates With C3030 series Male housing

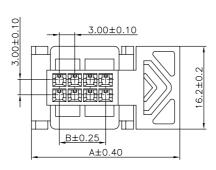


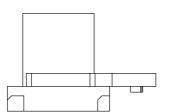
	Circuit	Dimensio	ons(mm)	Circuit	Dimensions(mm)		
		Α	В	Circuit	Α	В	
	2*01		3.95	2*07	18.00	21.95	
	2*02		6.95	2*08	21.00	24.95	
	2*03	6.00	9.95	2*09	24.00	27.95	
	2*04	9.00	12.95	2*10	27.00	30.95	
	2*05	12.00	15.95	2*11	30.00	33.95	
	2*06	15.00	18.95	2*12	33.00	36.95	

C3030H2F-2XXX0

Pitch 3.00mm Double row Housing

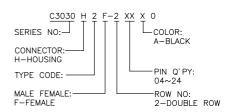






Specifications

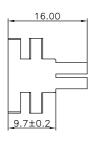
MATERIAL SPECIFICATION: Housing: PA66,94V-0 Suitable C3030 series Terminal Mates With C3030 series Male housing

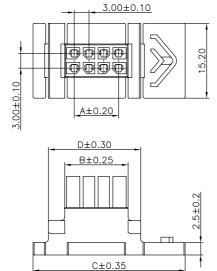


Circuit	Dimensio	ons(mm)	Circuit	Dimensions(mm)		
Circuit	Α	В	Circuit	Α	В	
2*02	22.84		2*08	40.84	21.00	
2*03	25.84	6.00	2*09	43.84	24.00	
2*04	28.84	9.00	2*10	46.84	27.00	
2*05	31.84	12.00	2*11	49.84	30.00	
2*06	34.84	15.00	2*12	52.84	33.00	
2*07	37.84	18.00				

C3030H3M-2XXX0

Pitch 3.00mm Double row Housing

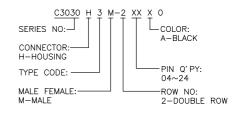




Specifications

MATERIAL SPECIFICATION: Housing: PA66,94V-0

Suitable C3030 series Terminal Mates With C3030 series Wafer

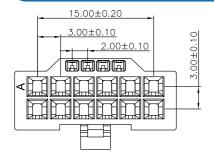


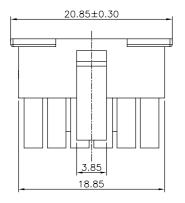
Circuit	Dimensions(mm)				Circuit	Dimensions(mm)				
Circuit	Α	В	С	D	Circuit	Α	В	С	О	
2*02		6.85	24.80	12.60	2*08	21.00	24.85	42.80	30.60	
2*03	6.00	9.85	27.80	15.60	2*09	24.00	27.85	45.80	33.60	
2*04	9.00	12.85	30.80	18.60	2*10	27.00	30.85	48.80	36.60	
2*05	12.00	15.85	33.80	21.60	2*11	30.00	33.85	51.80	39.60	
2*06	15.00	18.85	36.80	24.60	2*12	33.00	36.85	54.80	42.60	
2*07	18.00	21.85	39.80	27.60						

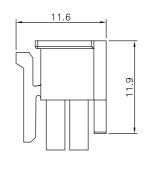


C3030H2M-2XXXX

Pitch 3.00mm Double row Housing



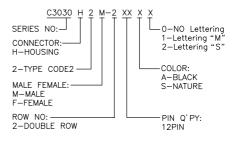




Specifications

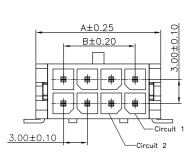
MATERIAL SPECIFICATION: Housing: PA66,94V-0

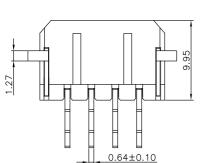
Suitable C3030 series Terminal Mates With C3030 series Wafer

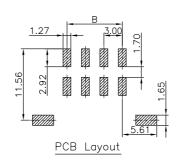


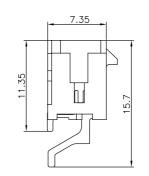
C3030W9-2XX2XX0

-Pitch 3.00mm 90° Double row SMT Wafer







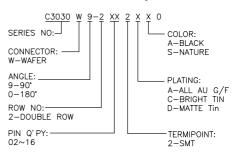


Specifications

MATERIAL SPECIFICATION: Housing: LCP,94V-0 Contacts: Brass

PLATING SPECIFICATION: Contacts:Matte tin

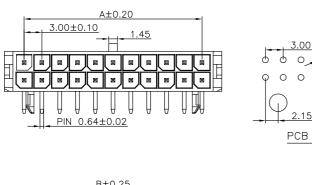
Mates with C3030 series housing

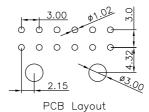


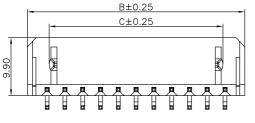
Circuit	Dimensi	ons(mm)	Circuit	Dimensions(mm)		
Oncare	Α	В	Circuit	Α	В	
2*01	6.65		2*07	24.65	18.00	
2*02	9.65		2*08	27.65	21.00	
2*03	12.65	6.00	2*09	30.65	24.00	
2*04	15.65	9.00	2*10	33.65	27.00	
2*05	18.65	12.00	2*11	36.65	30.00	
2*06	21.65	15.00	2*12	39.65	33.00	

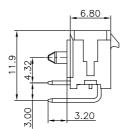
C3030W9-2XX1XX0

-Pitch 3.00mm 90° Double row DIP Wafer









Specifications

MATERIAL SPECIFICATION:
Housing: LCP,94V-0
Contacts: Brass

PLATING SPECIFICATION:
Contacts:Bright tin

Mates with C3030 series housing

C3030 W 9-2 XX 1 X X 0

SERIES NO:

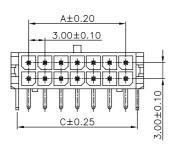
CONNECTOR:
CONNECTOR:
W-WAFFR

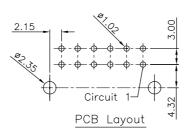
C3030 W 9-2	AA
SERIES NO: CONNECTOR: W-WAFER	COLOR: A-BLACK S-NATURE
ANGLE: 9-90* 0-180*	PLATING: A-ALL AU G/F C-BRIGHT TIN
ROW NO: 2-DOUBLE ROW	D-MATTE TIN
PIN Q' PY:	TERMIPOINT: 1-DIP

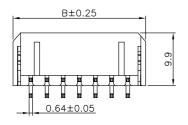
Dimensions ((mm) Circuit		Dimensions (mm)		
A	В	O	Circuit	Α	В	O
6	.65	3.55	2*07	18.00	24.65	17.30
9	.65	3.55	2*08	21.00	27.65	20.30
.00 12	2.65	3.55	2*09	24.00	30.65	23.30
.00 15	5.65	8.30	2*10	27.00	33.65	26.30
.00 18	3.65	11.30	2*11	30.00	36.65	29.30
.00 21	1.65	14.30	2*12	33.00	39.65	32.30
	9 00 12 .00 15	6.65 9.65 .00 12.65 .00 15.65 .00 18.65	A B C 6.65 3.55 9.65 3.55 00 12.65 3.55 .00 15.65 8.30	A B C	A B C A 6.65 3.55 2*07 18.00 9.65 3.55 2*08 21.00 00 12.65 3.55 2*09 24.00 .00 15.65 8.30 2*10 27.00 .00 18.65 11.30 2*11 30.00	A B C A B 6.65 3.55 2*07 18.00 24.65 9.65 3.55 2*08 21.00 27.65 00 12.65 3.55 2*09 24.00 30.65 00 15.65 8.30 2*10 27.00 33.65 .00 18.65 11.30 2*11 30.00 36.65

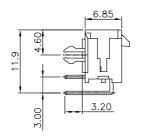
C3030W91-2XX1XX0

Pitch 3.00mm 90° Double row DIP Wafer







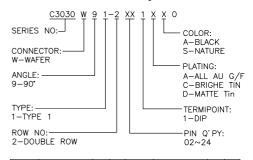


Specifications

MATERIAL SPECIFICATION: Housing: LCP,94V-0 Contacts: Brass

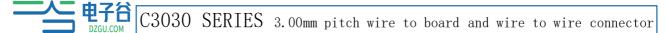
PLATING SPECIFICATION: Contacts:Bright tin

Mates with C3030 series housing



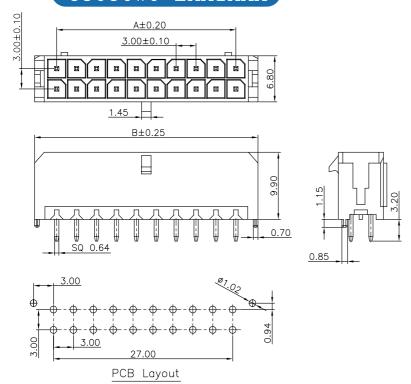
	Circuit	Dime	nsions(r	mm)	Circuit	Dimer	nsions(ı	mm)
	Circuit	Α	T B T C		Circuit	Α	В	С
	2*01		6.65	4.30	2*07	18.00	24.65	22.30
	2*02		9.65	7.30	2*08	21.00	27.65	25.30
ı	2*03	6.00	12.65	10.30	2*09	24.00	30.65	28.30
ı	2*04	9.00	15.65	13.30	2*10	27.00	33.65	31.30
ı	2*05	12.00	18.65	16.30	2*11	30.00	36.65	34.30
ı	2*06	15.00	21.65	19.30	2*12	33.00	39.65	37.30

220



C3030W0-2XX1XXX

-Pitch 3.00mm 180° Double row DIP Wafer

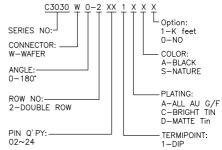


Specifications

MATERIAL SPECIFICATION: Housing: LCP,94V-0 Contacts: Brass

PLATING SPECIFICATION: Contacts:Bright tin

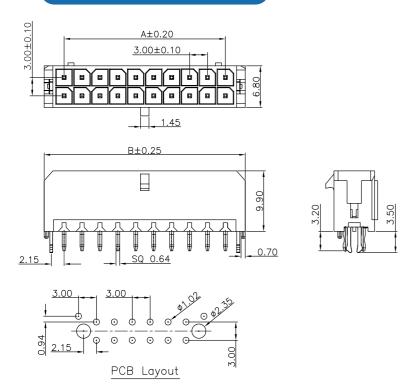
Mates with C3030 series housing



	Circuit	Dimension	ns(mm)	Circuit	Dimensions(mm)		
1	Circuit	Α	В	Circuit	Α	В	
	2*01		6.65		18.00	24.65	
	2*02		9.65	2*08	21.00	27.65	
ı	2*03	6.00	12.65	2*09	24.00	30.65	
	2*04	9.00	15.65	2*10	27.00	33.65	
I	2*05	12.00	18.65	2*11	30.00	36.65	
	2*06	15.00	21.65	2*12	33.00	39.65	

C3030W01-2XX1XXX

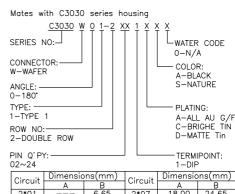
-Pitch 3.00mm 180° Double row DIP Wafer



Specifications

MATERIAL SPECIFICATION: Housing: LCP,94V-0 Contacts: Brass

PLATING SPECIFICATION: Contacts:Matte tin



Circuit	Dimensio	ns(mm)	Circuit	Dimensions(mm)		
Circuit	Α	В	Circuit	Α	В	
2*01		6.65	2*07	18.00	24.65	
2*02		9.65	2*08	21.00	27.65	
2*03	6.00	12.65	2*09	24.00	30.65	
2*04	9.00	15.65	2*10	27.00	33.65	
2*05	12.00	18.65	2*11	30.00	36.65	
2*06	15.00	21.65	2*12	33.00	39.65	

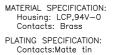
Ø 0.15

11.40

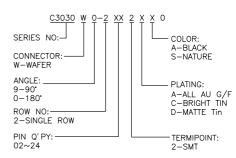
C3030W0-2XX2XX0

Pitch 3.00mm 180° Double row SMT Wafer

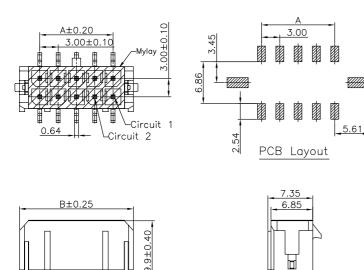
Specifications



Mates with C3030 series housing



Circuit	Dimensi	ons(mm)	Circuit	Dimensi	Dimensions(mm)		
Circuit	Α	В	Circuit	Α	В		
2*01		6.65	2*07	18.00	24.65		
2*02		9.65	2*08	21.00	27.65		
2*03	6.00	12.65	2*09	24.00	30.65		
2*04	9.00	15.65	2*10	27.00	33.65		
2*05	12.00	18.65	2*11	30.00	36.65		
2*06	15.00	21.65	2*12	33.00	39.65		

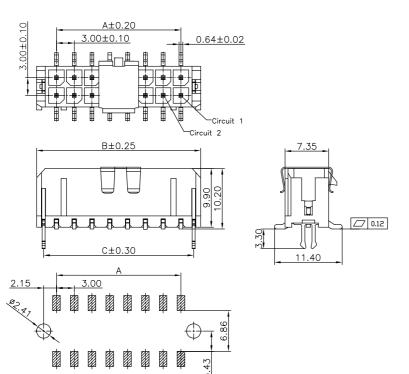


C3030W01-2XX2XX0

A

PCB_Layout

-Pitch 3.00mm 180° Double row SMT Wafer

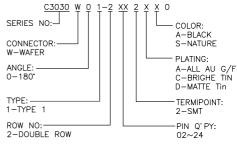


Specifications

MATERIAL SPECIFICATION: Housing: LCP,94V-0 Contacts: Brass

PLATING SPECIFICATION: Contacts:Matte tin

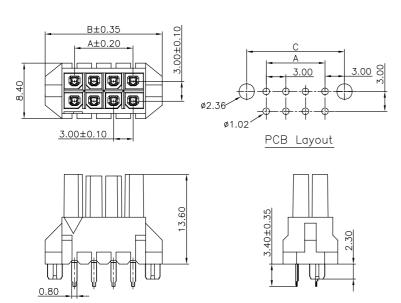
Mates with C3030 series housing



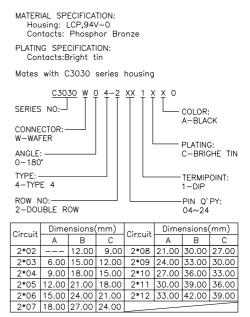
Circuit	Dimensions(mm)			Circuit	Dimensions(mm)			
Circuit	Α	В	C	Circuit	Α	В	С	
2*01		6.65	4.30	2*07	18.00	24.65	22.30	
2*02		9.65	7.30	2*08	21.00	27.65	25.30	
2*03	6.00	12.65	10.30	2*09	24.00	30.65	28.30	
2*04	9.00	15.65	13.30	2*10	27.00	33.65	31.30	
2*05	12.00	18.65	16.30	2*11	30.00	36.65	34.30	
2*06	15.00	21.65	19.30	2*12	33.00	39.65	37.30	

C3030W04-2XX1XX0

Pitch 3.00mm 180° Double row DIP Wafer

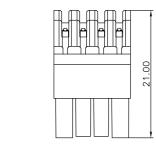


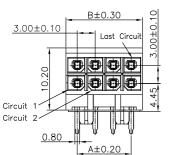
Specifications

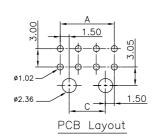


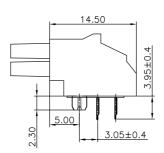
C3030W94-2XX1XX0

Pitch 3.00mm 90° Double row DIP Wafer







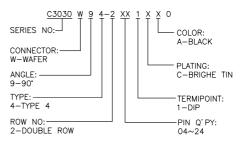


Specifications

MATERIAL SPECIFICATION: Housing: LCP,94V-0 Contacts: Phosphor Bronze

PLATING SPECIFICATION: Contacts:Bright tin

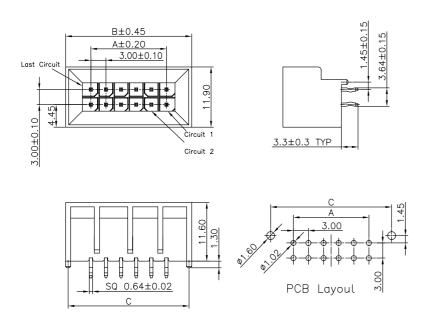
Mates with C3030 series housing



Circuit	Dimensions(mm)			Circuit	Dimensions(mm)		
Circuit	Α	В	С	Circuit	Α	В	С
2*02		6.70		2*08	21.00	24.70	18.00
2*03	6.00	9.70		2*09	24.00	27.70	21.00
2*04	9.00	12.70	6.00	2*10	27.00	30.70	24.00
2*05	12.00	15.70	9.00	2*11	30.00	33.70	27.00
2*06	15.00	18.70	12.00	2*12	33.00	36.70	30.00
2*07	18.00	21.70	15.00				

C3030W05-2XX1XX0

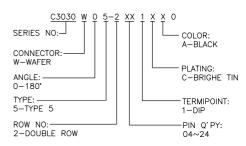
Pitch 3.00mm 180° Double row DIP Wafer



Specifications

MATERIAL SPECIFICATION:
Housing: LCP,94V-0
Contacts: Phosphor Bronze
PLATING SPECIFICATION:
Contacts:Bright tin

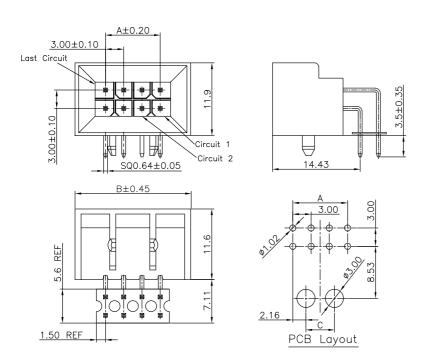
Mates with C3030 series housing



Ι,	Circuit	Dimensions(mm)		(mm)	Circuit	Dimensions(mm)		
T,		Α	В	С		Α	В	c
	2*02		13.00	12.00	2*08	21.00	31.00	30.00
	2*03	6.00	16.00	15.00	2*09	24.00	34.00	33.00
	2*04	9.00	19.00	18.00	2*10	27.00	37.00	36.00
Г	2*05	12.00	22.00	21.00	2*11	30.00	40.00	39.00
	2*06	15.00	25.00	24.00	2*12	33.00	43.00	42.00
	2*07	18.00	28.00	27.00				

C3030W95-2XX1XX0

Pitch 3.00mm 90° Double row DIP Wafer

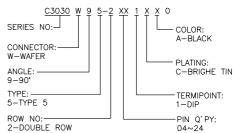


Specifications

MATERIAL SPECIFICATION: Housing: LCP,94V-0 Contacts: Phosphor Bronze

PLATING SPECIFICATION: Contacts:Bright tin

Mates with C3030 series housing



Circuit	Dime	Dimensions(mm)			Dimensions(mm)		
Circuit	Α	В	С	Circuit	Α	В	С
2*02		13.00		2*08	21.00	31.00	16.68
2*03	6.00	16.00		2*09	24.00	34.00	19.68
2*04	9.00	19.00	4.68	2*10	27.00	37.00	22.68
2*05	12.00	22.00	7.68	2*11	30.00	40.00	25.68
2*06	15.00	25.00	10.68	2*12	33.00	43.00	28.68
2*07	18.00	28.00	13.68				

C3030W91-2XX2XX0

Pitch 3.00mm 90° Double row SMT Wafer

C±0.20 3.00±0.10 Circuit 2 Final Augustian Street Stree

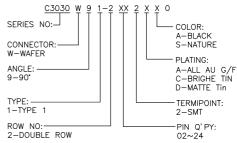
Specifications

MATERIAL SPECIFICATION:
Housing: LCP,94V-0
Contacts: Brass

PLATING SPECIFICATION:
Contacts:Matte tin

Mates with C3030 series housing

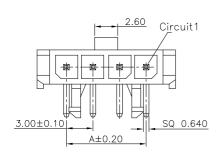
Mates with C3030 series housing

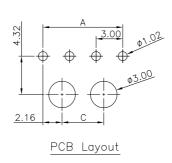


Circuit	Dimensions(mm)			Circuit	Dimensions(mm)			
	Α	В	С	Circuit	Α	В	С	
2*01		6.65	4.30	2*07	18.00	24.65	22.30	
2*02		9.65	7.30	2*08	21.00	27.65	25.30	
2*03	6.00	12.65	10.30	2*09	24.00	30.65	28.30	
2*04	9.00	15.65	13.30	2*10	27.00	33.65	31.30	
2*05	12.00	18.65	16.30	2*11	30.00	36.65	34.30	
2*06	15.00	21.65	19.30	2*12	33.00	39.65	37.30	

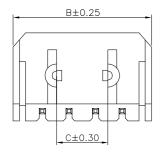
C3030W9-1XX1XX0

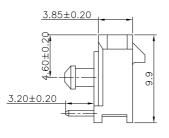
-Pitch 3.00mm 90° Single row DIP Wafer





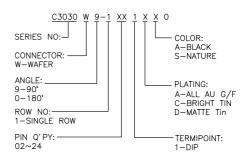
PCB Layout





Specifications

MATERIAL SPECIFICATION:
Housing: LCP,94V-0
Contacts: Brass
PLATING SPECIFICATION:
Contacts:Bright tin
Mates with C3030 series housing

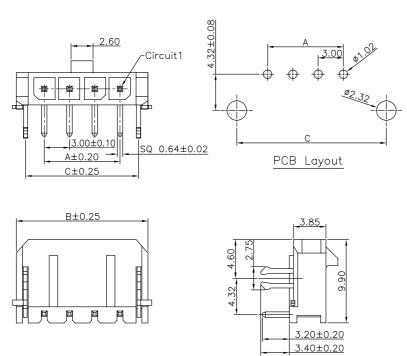


Circuit	Dimensions(mm)			Circuit	Dimensions(mm)		
Circuit	Α	В	С	Circuit	Α	В	С
01		6.65		07	18.00	24.65	13.70
02		9.65		08	21.00	27.65	16.70
03	6.00	12.65		09	24.00	30.65	19.70
04	9.00	15.65	4.70	10	27.00	33.65	22.70
05	12.00	18.65	7.70	11	30.00	36.65	25.70
06	15.00	21.65	10.70	12	33.00	39.65	28.70



C3030W91-1XX1XX0

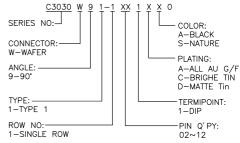
Pitch 3.00mm 90° Single row DIP Wafer



Specifications

MATERIAL SPECIFICATION: Housing: LCP,94V-0 Contacts: Brass PLATING SPECIFICATION: Contacts:Bright tin

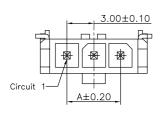
Mates with C3030 series housing

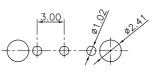


Circuit	Dimensions(mm)			Circuit	Dimensions(mm)		
Circuit	Α	В	С	Circuit	Α	В	O
01		6.65	4.30	07	18.00	24.65	21.30
02		9.65	7.30	08	21.00	27.65	24.30
03	6.00	12.65	10.30	09	24.00	30.65	27.30
04	9.00	15.65	13.30	10	27.00	33.65	30.30
05	12.00	18.65	16.30	11	30.00	36.65	33.30
06	15.00	21.65	19.30	12	33.00	39.65	36.30

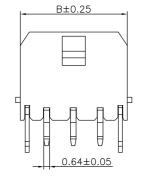
C3030W0-1XX1XX0

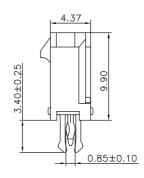
-Pitch 3.00mm 180° Single row DIP Wafer





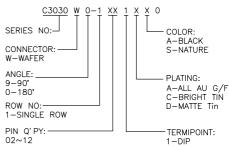
PCB Layout



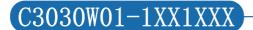


Specifications

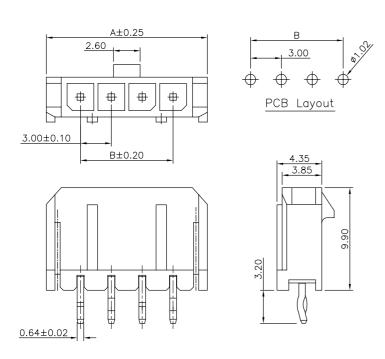
MATERIAL SPECIFICATION: Housing: LCP,94V-0 Contacts: Brass PLATING SPECIFICATION: Contacts:Bright tin Mates with C3030 series housing



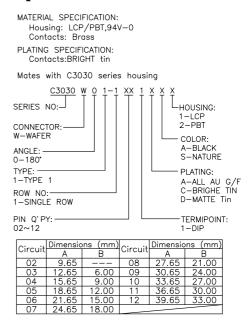
Circuit	Dimensio	ons(mm)	C::	Dimensions(mm)		
Circuit	Α	В	Circuit	Α	В	
02		9.65	08	21.00	27.65	
03	6.00	12.65	09	24.00	30.65	
04	9.00	15.65	10	27.00	33.65	
05	12.00	18.65	11	30.00	36.65	
06	15.00	21.65	12	33.00	39.65	
07	18.00	24.65				



Pitch 3.00mm 180° Single row DIP Wafer

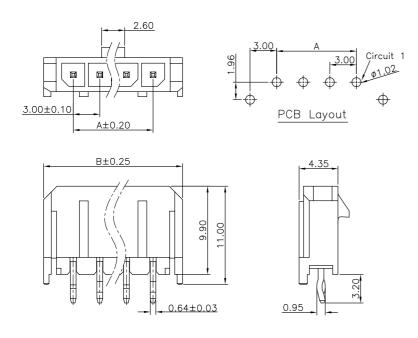


Specifications

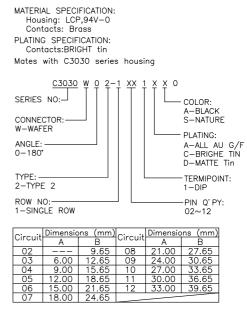


C3030W02-1XX1XX0

Pitch 3.00mm 180° Single row DIP Wafer

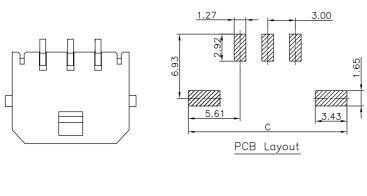


Specifications

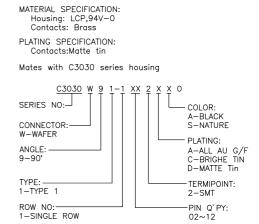


C3030W91-1XX2XX0

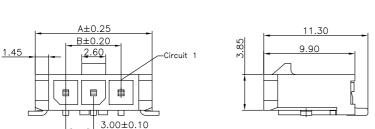
Pitch 3.00mm 90° Single row SMT Wafer



Specifications

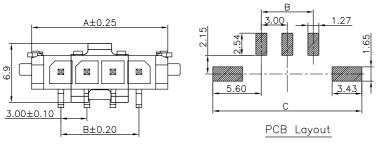


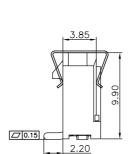
Circuit	Dimensions(mm)			Circuit	Dimensions(mm)		
	Α	В	С		Α	В	С
02	9.65		14.20	08	27.65	21.00	32.20
03	12.65	6.00	17.20	09	30.65	24.00	35.20
04	15.65		20.20	10	33.65	27.00	38.20
05	18.65	12.00	23.20	11	36.65	30.00	41.20
06	21.65	15.00	26.20	12	39.65	33.00	44.20
07	24.65	18.00	29.20				



C3030W0-1XX2XX0

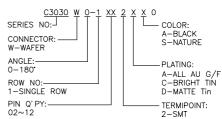
-Pitch 3.00mm 180° Single row SMT Wafer





Specifications

MATERIAL SPECIFICATION:
Housing: LCP,94V-0
Contacts: Brass
PLATING SPECIFICATION:
Contacts:Matte tin
Mates with C3030 series housing



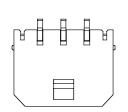
	Circuit	Dimensions(mm)			Circuit	Dimensions(mm)		
		Α	В	С		A	В	С
	02	9.70		14.20	08	27.70	21.00	32.20
	03	12.70	6.00	17.20	09	30.70	24.00	35.20
	04	15.70	9.00	20.20	10	33.70	27.00	38.20
	05	18.70	12.00	23.20	11	36.70	30.00	41.20
	06	21.70	15.00	26.20	12	39.70	33.00	44.20
	07	24.70	18.00	29.20				

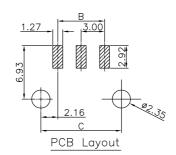


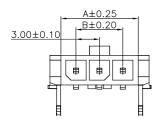
C3030 SERIES 3.00mm pitch wire to board and wire to wire connector

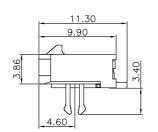
C3030W9-1XX2XX0

Pitch 3.00mm 90° Single row SMT Wafer





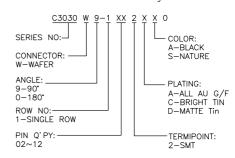




Specifications

MATERIAL SPECIFICATION:
Housing: LCP,94V-0
Contacts: Brass
PLATING SPECIFICATION:
Contacts:Matte tin

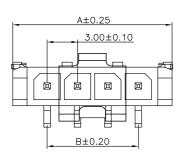
Mates with C3030 series housing

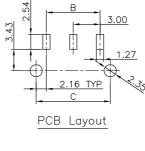


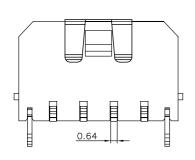
Circuit	Dimensions (mm)			Circuit	Dimensions ((mm)
Circuit	Α	В	С	Circuit	Α	В	C
02	6.85		7.30	08	24.85	21.00	25.30
03	9.85	6.00	10.30	09	27.85	24.00	28.30
04	12.85	9.00	13.30	10	30.85	27.00	31.30
05	15.85	12.00	16.30	11	33.85	30.00	34.30
06	18.85	15.00	19.30	12	36.85	33.00	37.30
07	21.85	18.00	22.30				

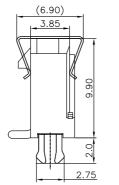
C3030W01-1XX2XX0

-Pitch 3.00mm 180° Single row SMT Wafer



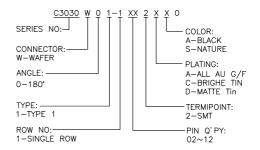






Specifications

MATERIAL SPECIFICATION:
Housing: LCP,94V-0
Contacts: Brass
PLATING SPECIFICATION:
Contacts:Matte tin
Mates with C3030 series housing



Circuit	Dimensions (mm)			C:1	Dimensions (mm)		
Circuit	Α	В	С	Circuit	Α	В	С
02	9.65		7.30	08	27.65	21.00	25.30
03	12.65	6.00	10.30	09	30.65	24.00	28.30
04	15.65	9.00	13.30	10	33.65	27.00	31.30
05	18.65	12.00	16.30	11	36.65	30.00	34.30
06	21.65	15.00	19.30	12	39.65	33.00	37.30
07	24.65	18.00	22.30				

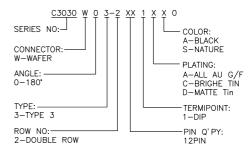
C3030W03-2XX1XX0

Pitch 3.00mm 180° Double row DIP Wafer

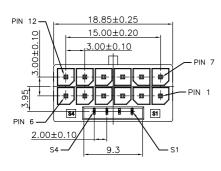
Specifications

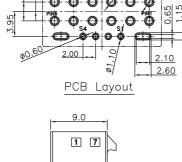


Mates with C3030 series housing



PIN SIGNAL	PIN NO.
PWR	1~6
GND	7~12
S1	CARD_PWR_STABLE
S2	CARD_CBL_PRES#
S3	SENSE0
S4	DO NOT USF

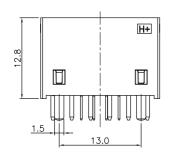


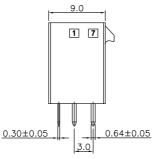


15.00

7.50

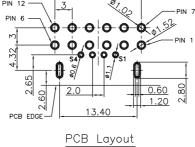
1.50

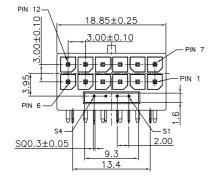


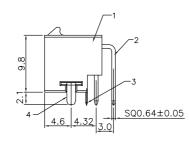


C3030W93-2XX1XX0

-Pitch 3.00mm 90° Double row DIP Wafer

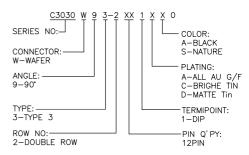






Specifications

MATERIAL SPECIFICATION:
Housing: PA9T,94V-0
Contacts: High Conductivity Copper C1100
PLATING SPECIFICATION:
Contacts:Matte tin
Mates with C3030 series housing



PIN SIGNAL	PIN NO.
PWR PIN	1~6
GND PIN	7~12
S1	CARD_PWR_STABLE
S2	CARD_CBL_PRES#
S3	SENSE0
S4	DO NOT USF